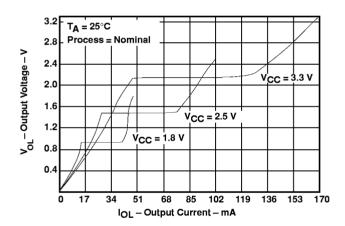
- EPIC[™] (Enhanced-Performance Implanted CMOS) Submicron Process
- DOC™ (Dynamic Output Control) Circuit Dynamically Changes Output Impedance, Resulting in Noise Reduction Without Speed Degradation
- Dynamic Drive Capability Is Equivalent to Standard Outputs With I_{OH} and I_{OL} of ±24 mA at 2.5-V V_{CC}
- Overvoltage-Tolerant Inputs/Outputs Allow Mixed-Voltage-Mode Data Communications
- Package Options Include Plastic Small-Outline (D), Thin Very Small-Outline (DGV), and Thin Shrink Small-Outline (PW) Packages

description

A Dynamic Output Control (DOC) circuit is implemented, which, during the transition, initially lowers the output impedance to effectively drive the load and, subsequently, raises the impedance to reduce noise. Figure 1 shows typical V_{OL} vs I_{OL} and V_{OH} vs I_{OH} curves to illustrate the output impedance and drive capability of the circuit. At the beginning of the signal transition, the DOC circuit provides a maximum dynamic drive that is equivalent to a high-drive standard-output device. For more information, refer to the TI application reports, *AVC Logic Family Technology and Applications*, literature number SCEA006, and *Dynamic Output Control (DOC*TM) *Circuitry Technology and Applications*, literature number SCEA009.



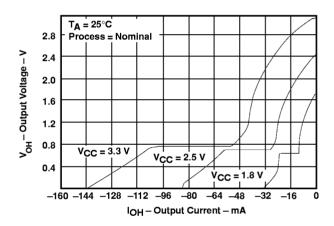


Figure 1. Output Voltage vs Output Current

This triple 3-input positive-NAND gate is operational at 1.2-V to 3.6-V V_{CC} , but designed specifically for 1.65-V to 3.6-V V_{CC} operation.

The SN74AVC10 performs the Boolean function $Y = \overline{A \cdot B \cdot C}$ or $Y = \overline{A} + \overline{B} + \overline{C}$ in positive logic.

The SN74AVC10 is characterized for operation from -40°C to 85°C.



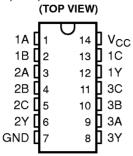
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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terminal assignments

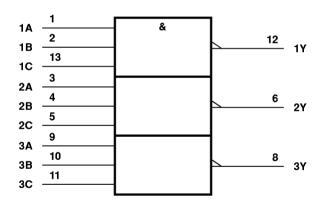
D, DGV, OR PW PACKAGE



FUNCTION TABLE (each gate)

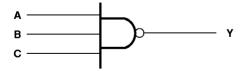
	INPUTS		OUTPUT
Α	В	С	Y
Ι	Н	Н	L
L	Х	Χ	Н
Х	L	Χ	Н
Х	Х	L	Н

logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram, each gate (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, Voc	
117 0 0	
Input clamp current, $I_{ K }(V_{ C } < 0)$	
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Continuous output current, IO	±50 mA
Continuous current through each V _{CC} or GND	±100 mA
	kage 127°C/W
- · · · · · · · · · · · · · · · · · · ·	package 182°C/W
·	ackage 170°C/W
•	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

- 2. The output positive-voltage rating may be exceeded up to 4.6 V maximum if the output current rating is observed.
- 3. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT	
V	Supply valtage	Operating	1.65	3.6	V	
vcc	Supply voltage	Data retention only	1.2		V	
		V _{CC} = 1.2 V	Vcc			
V	High level inner veltage	$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	0.65 × V _{CC}		v	
V_{IH}	High-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		V	
		$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$	2			
		V _{CC} = 1.2 V		GND		
V	V _{IL} Low-level input voltage	V _{CC} = 1.65 V to 1.95 V		0.35 × V _{CC}	V	
۷IГ		V _{CC} = 2.3 V to 2.7 V		0.7		
		V _{CC} = 3 V to 3.6 V		0.8		
VI	Input voltage	·	0	3.6	٧	
\/_	Outrotteration	Active state	0	Vcc	٧	
Vo	Output voltage	3-state	0	3.6	٧	
		V _{CC} = 1.65 V to 1.95 V		-4		
lohs	Static high-level output current‡	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		-8	mA	
		V _{CC} = 3 V to 3.6 V		-12		
		V _{CC} = 1.65 V to 1.95 V		4		
lols	IOLS Static low-level output current [‡]	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		8	mA	
		V _{CC} = 3 V to 3.6 V		12		
Δt/Δv	Input transition rise or fall rate	V _{CC} = 1.65 V to 3.6 V		5	ns/V	
TA	Operating free-air temperature	<u>. </u>	-40	85	°C	

[‡] Dynamic drive capability is equivalent to standard outputs with I_{OH} and I_{OL} of ±24 mA at 2.5-V V_{CC}. See Figure 1 for V_{OL} vs I_{OL} and V_{OH} vs I_{OH} characteristics. Refer to the TI application reports, *AVC Logic Family Technology and Applications*, literature number **SCEA006**, and *Dynamic Output Control (DOC*[™]) *Circuitry Technology and Applications*, literature number **SCEA009**.

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs. literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		v _{cc}	MIN	TYP†	MAX	UNIT
	I _{OHS} = -100 μA		1.65 V to 3.6 V	V _{CC} -0.	2		
Vou	$I_{OHS} = -4 \text{ mA},$	V _{IH} = 1.07 V	1.65 V	1.2			v
Voн	$I_{OHS} = -8 \text{ mA},$	V _{IH} = 1.7 V	2.3 V	1.75			v
	$I_{OHS} = -12 \text{ mA},$	V _{IH} = 2 V	3 V	2.3			
	I _{OLS} = 100 μA		1.65 V to 3.6 V			0.2	
Va.	I _{OLS} = 4 mA,	$V_{IL} = 0.57 V$	1.65 V			0.45	v I
VoL	I _{OLS} = 8 mA,	$V_{IL} = 0.7 V$	2.3 V			0.55	v
	$I_{OLS} = 12 \text{ mA},$	V _{IL} = 0.8 V	3 V			0.7	
lj	$V_I = V_{CC}$ or GND		3.6 V			±2.5	μΑ
Icc	$V_I = V_{CC}$ or GND,	I _O = 0	3.6 V			40	μΑ
0.	V _I = V _{CC} or GND		2.5 V				pF
C _i	AL = ACC OLGIND		3.3 V		•		þг

[†] Typical values are measured at T_A = 25°C.

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 2 through 6)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} =	1.2 V	V _{CC} =		V _{CC} = ± 0.1		V _{CC} =		V _{CC} =		UNIT
	(IIVFOI)	(OUTFUT)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
^t pd	A, B, or C	Υ											ns

operating characteristics, T_A = 25°C

PARAMETER		TEST CONDITIONS		V _{CC} = 1.8 V	$V_{CC} = 2.5 \text{ V}$	$V_{CC} = 3.3 \text{ V}$	UNIT	
	PARAMETER		TEST CONDITIONS		TYP	TYP	TYP	ONIT
[C _{pd}	Power dissipation capacitance per gate	C _L = 0,	f = 10 MHz				pF



PRODUCT PREVIEW

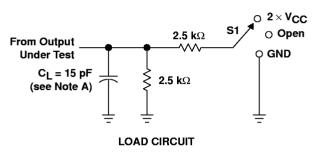
V_CC

0 V

V_{CC}/2

PARAMETER MEASUREMENT INFORMATION V_{CC} = 1.2 V

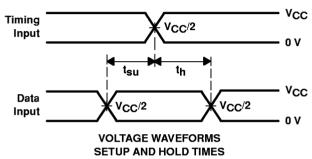
Input

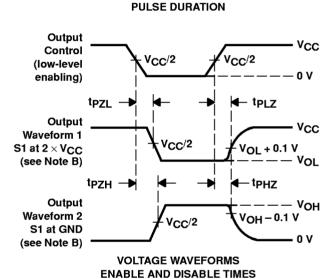


TEST	S1
tpd	Open
t _{PLZ} /t _{PZL}	2×V _{CC}
tPHZ/tPZH	GND

V_{CC}/2

VOLTAGE WAVEFORMS





Output

VCC/2

VCC/2

VCC/2

VCC/2

VCC/2

VOH

VCC/2

VOH

VCC/2

VOL

VOLTAGE WAVEFORMS

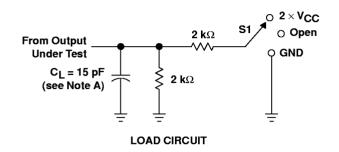
PROPAGATION DELAY TIMES

NOTES: A. C_L includes probe and jig capacitance.

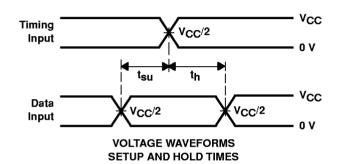
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f \leq$ 2 ns, $t_f \leq$ 2 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpl 7 and tpH7 are the same as t_{dis}.
- F. tpzL and tpzH are the same as ten.
- G. tplH and tpHL are the same as tod.

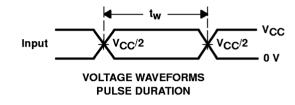
Figure 2. Load Circuit and Voltage Waveforms

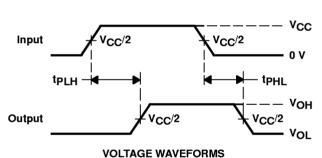
PARAMETER MEASUREMENT INFORMATION $V_{CC} = 1.5 \text{ V} \pm 0.1 \text{ V}$



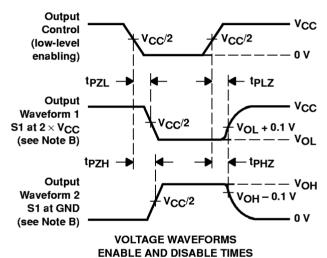
TEST	S1
t _{pd}	Open
t _{PLZ} /t _{PZL}	2×V _{CC}
tPHZ/tPZH	GND







PROPAGATION DELAY TIMES



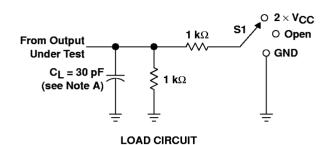
NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f \leq$ 2 ns, $t_f \leq$ 2 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis-
- F. tpzL and tpzH are the same as ten-
- G. tpLH and tpHL are the same as tpd.

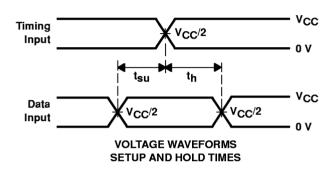
Figure 3. Load Circuit and Voltage Waveforms

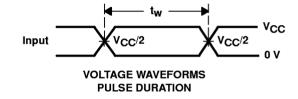


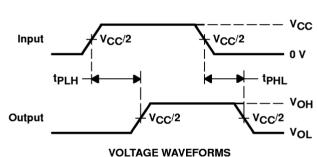
PARAMETER MEASUREMENT INFORMATION $V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}$



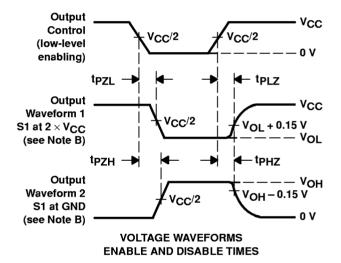
TEST	S1
tpd	Open
tPLZ/tPZL	2×V _{CC}
tPHZ/tPZH	GND







PROPAGATION DELAY TIMES

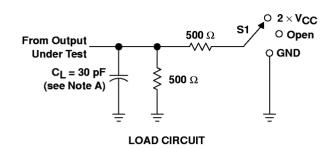


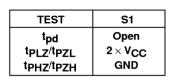
NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \ \Omega$, $t_f \leq 2 \ ns$, $t_f \leq 2 \ ns$.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tplH and tpHL are the same as tod.

Figure 4. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$



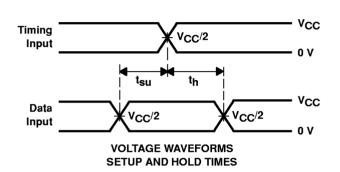


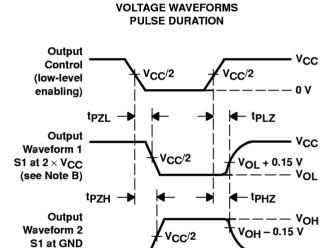
V_{CC}/2

Input

V_{CC}/2

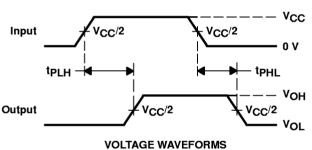
0 V





VOLTAGE WAVEFORMS

ENABLE AND DISABLE TIMES



PROPAGATION DELAY TIMES

- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \ \Omega$, $t_f \leq$ 2 ns. $t_f \leq$ 2 ns.

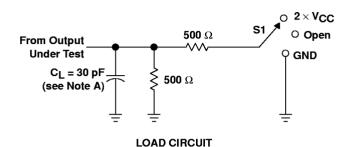
(see Note B)

- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

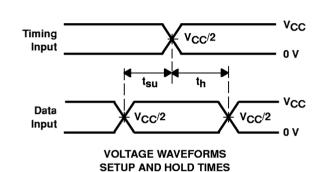
Figure 5. Load Circuit and Voltage Waveforms

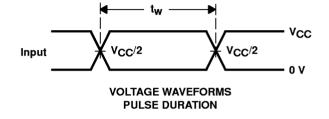
PRODUCT PREVIEW

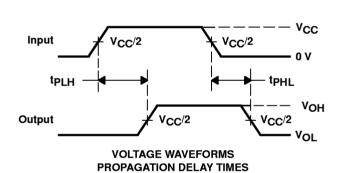
PARAMETER MEASUREMENT INFORMATION $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$

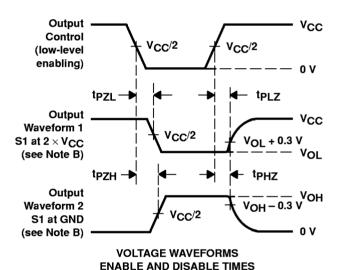


TEST	S1
^t pd	Open
t _{PLZ} /t _{PZL}	2×V _{CC}
^t PHZ ^{/t} PZH	GND









NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_{O} = 50 Ω , $t_{f} \leq$ 2 ns, $t_{f} \leq$ 2 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpl 7 and tpH7 are the same as tdis.
- F. tp_{ZL} and tp_{ZH} are the same as t_{en} .
- G. tpLH and tpHL are the same as tpd.

Figure 6. Load Circuit and Voltage Waveforms

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